



FRIENDSHIP SYSTEMS

# ***Optimization of an Additively Manufactured Inverter Cooling Plate for an Electric Vehicle***

*Giuseppe Cicalese, PhD*  
*R&D CFD*

*Ceyhan Erdem*  
*Friendship Systems*



R&D CFD is a former Spin-Off Company of

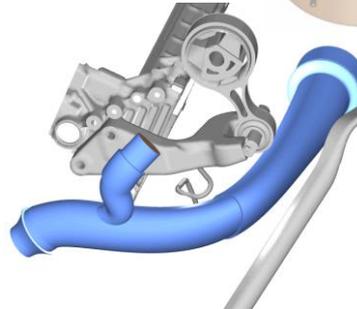
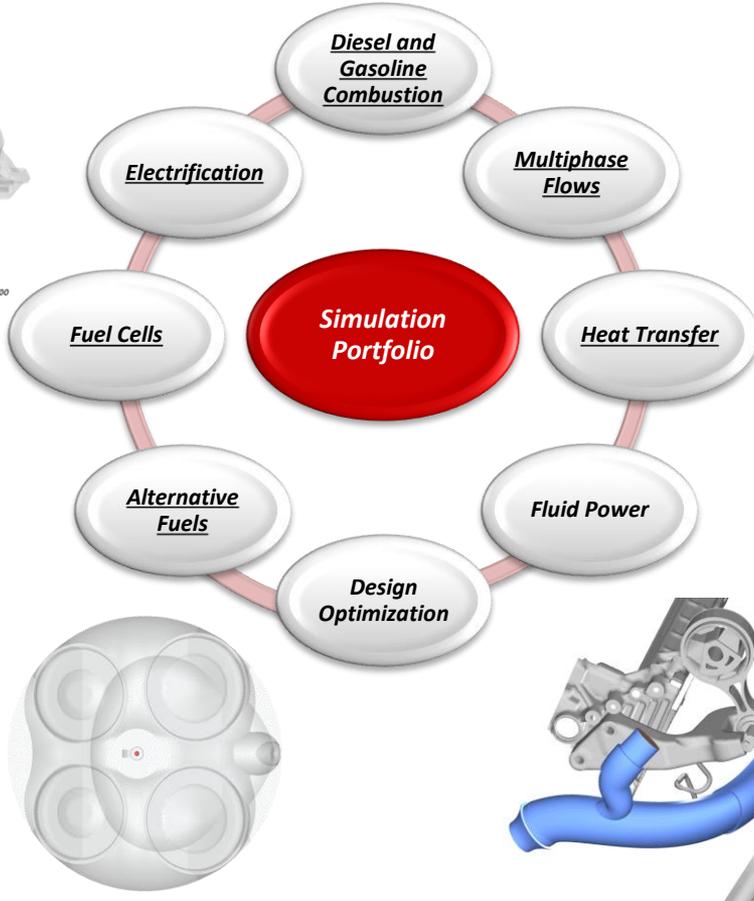
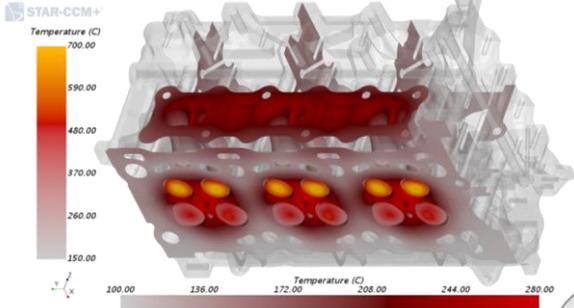
**UNIMORE**  
UNIVERSITÀ DEGLI STUDI DI  
MODENA E REGGIO EMILIA



- ✓ born in July 2012
- ✓ 7 CFD engineers + 5 high level CFD Specialists
- ✓ 500+ core HPC systems
- ✓ 4 funded PhD positions in 5 years
- ✓ engineering services for some of the most renowned automotive, food&beverage, healthcare, fluid-power companies
- ✓ Partner of  since 2016

FRIENDSHIP SYSTEMS





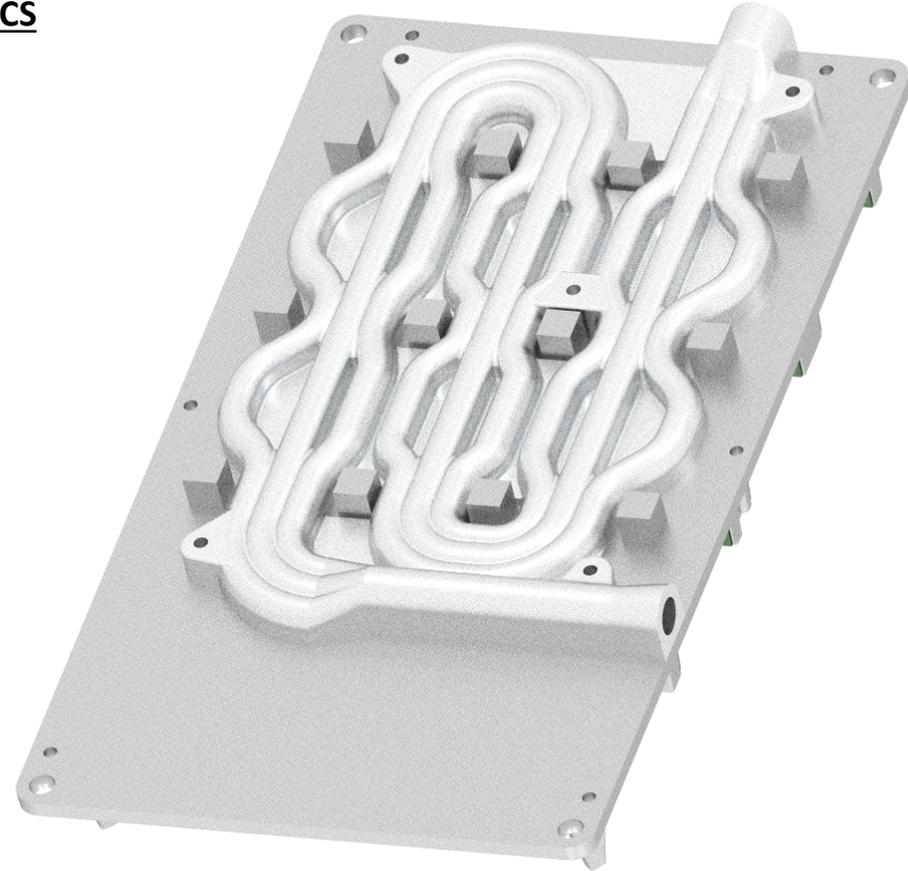
## MMR HYBRID F-SAE CAR: THE COOLING OF POWER ELECTRONICS

- MMR Hybrid is the team of University of Modena and Reggio Emilia participating in Formula SAE Hybrid
- The inverter devoted to control electrical power fluxes was originally intended to be cooled by air
- To increase its performance, a cold plate fed with water is purposely developed



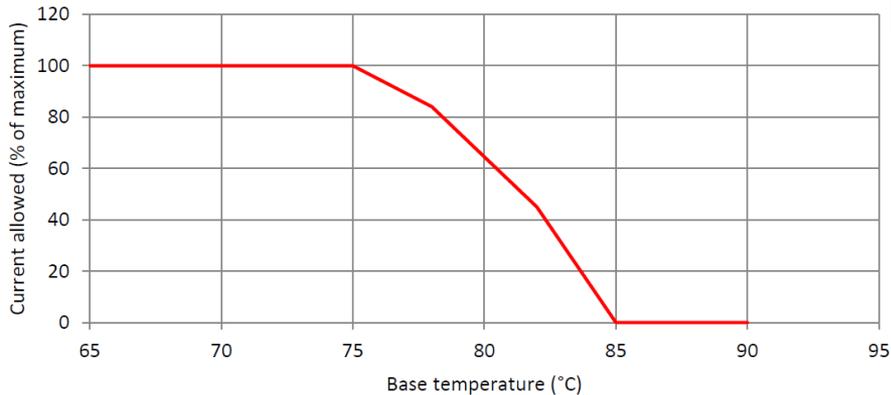
## MMR HYBRID F-SAE CAR: THE COOLING OF POWER ELECTRONICS

- The original cold plate was already enhanced through the testing of different layouts
- Thanks to additive manufacturing the design constraints are very limited (mainly related to minimum thickness of the metal and wall inclinations)
- Inlet and outlet locations are fixed due to the layout of the components

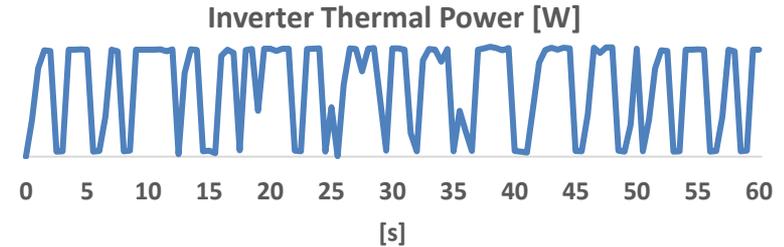


## The role of thermal management

- Power electronics performance depend on the thermal management of the components
- Max junction temperature for transistors: in-between 125 °C and 150 °C
- The base temperature of the inverter must not exceed 75 °C to avoid a huge reduction of the current



- ① Estimate of the power dissipated by the inverter by means of a Simulink model of the hybrid powertrain



- ② CFD simulation of 3 consecutive laps to monitor the thermal field of baseline design

Simcenter STAR-CCM+

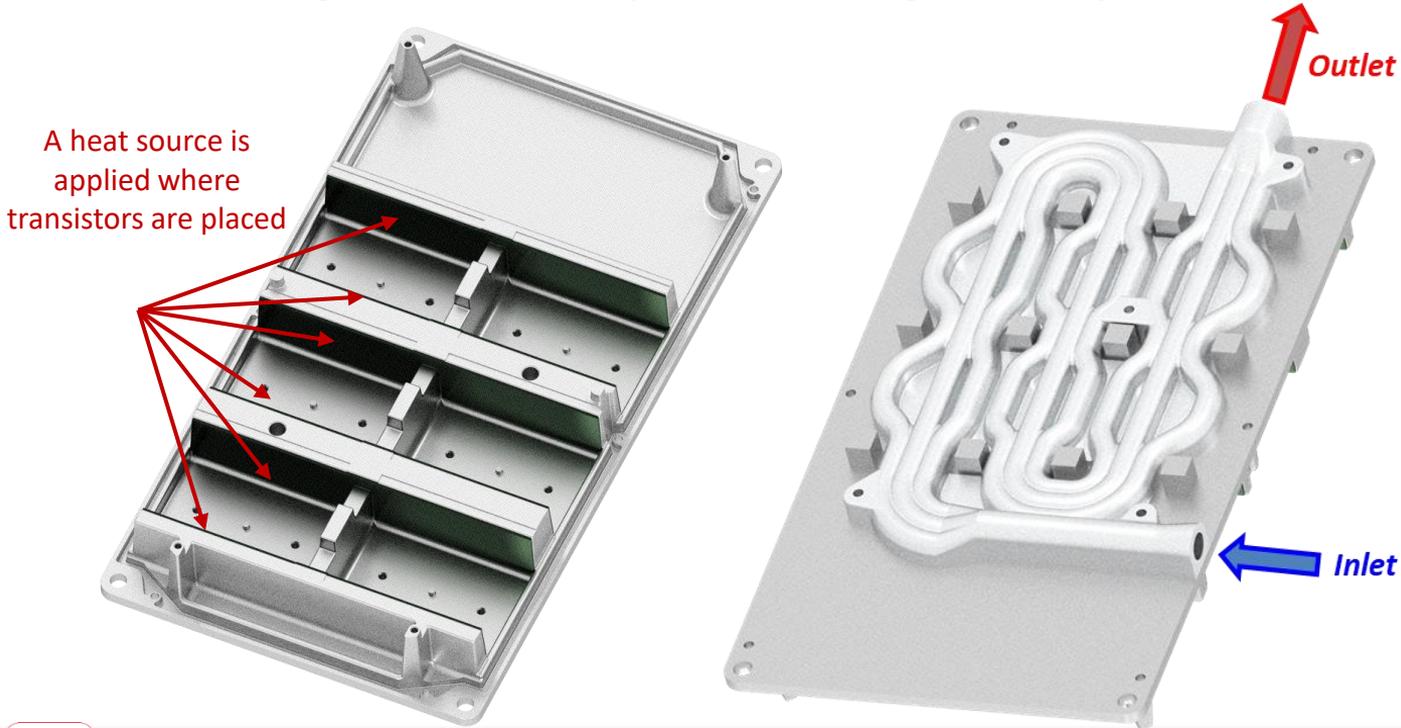
Solution Time 0.25 (s)



## 1. From unsteady to steady framework

- A steady state CHT CFD model is generated to speed up investigations → neglect of thermal inertia

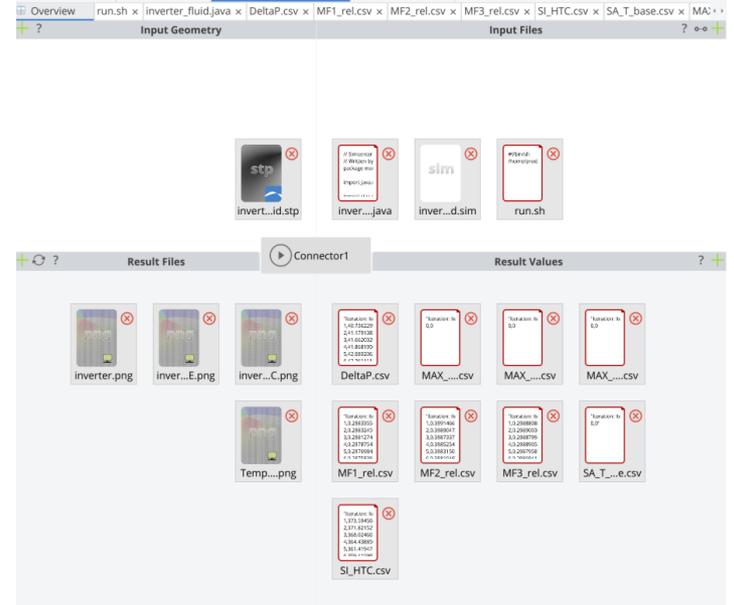
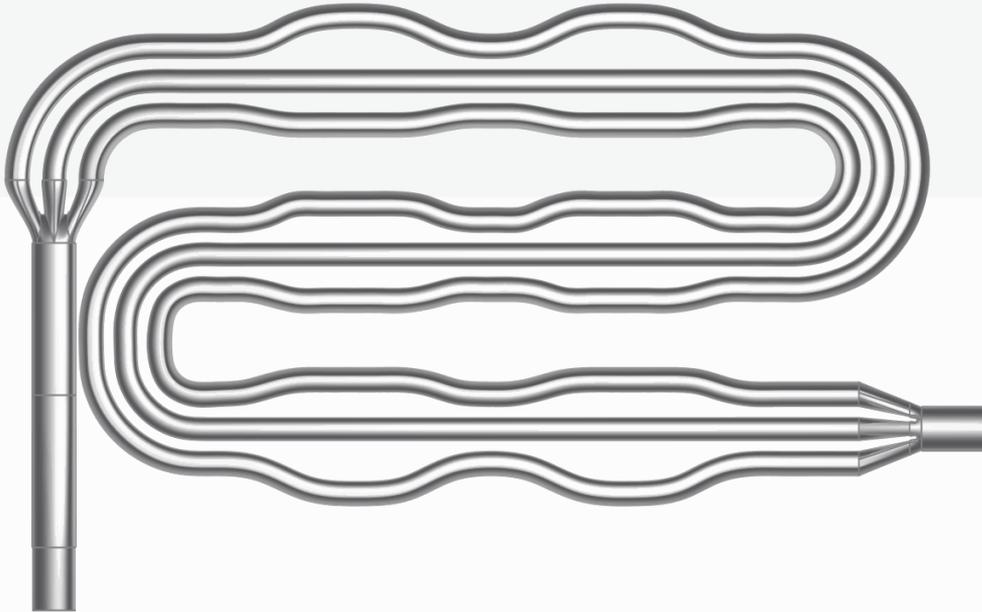
It was verified on single cases that the improvements emerge in a steady state framework as well



- 3 different materials
- Contact resistances
- Heat can be removed only by the coolant

## 2. Creation of a parametric model

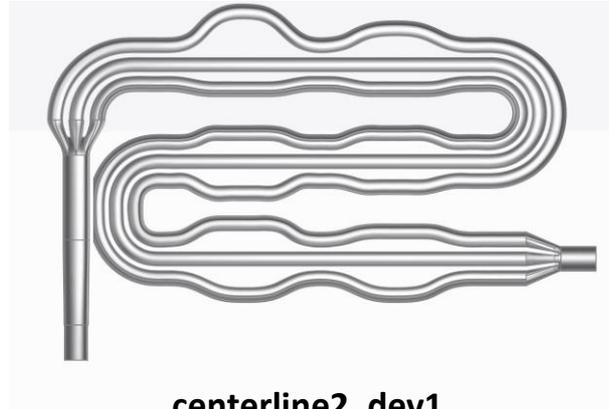
**CAESES** is connected to **STAR-CCM+** for the execution of CFD simulations



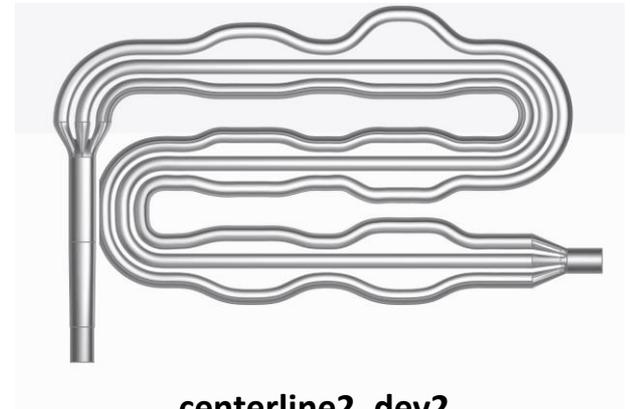
## 2. Creation of parametric models

Centerline parameters affect the way the cold plate surrounds the bolt seat of the inverter

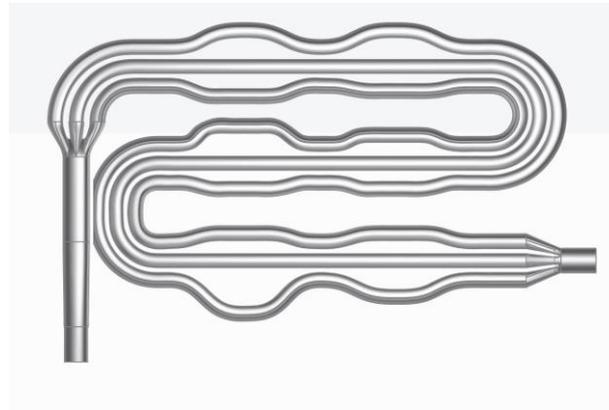
centerline1\_dev1



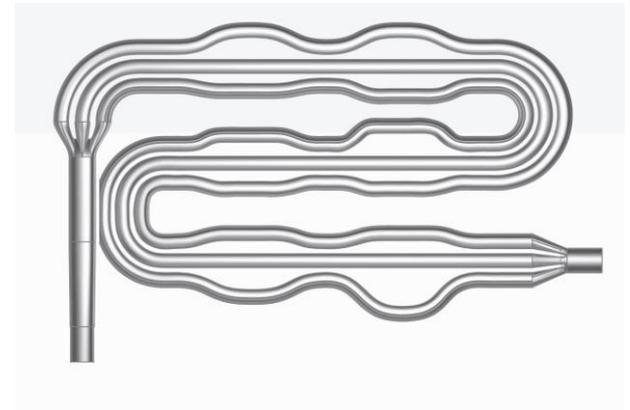
centerline1\_dev2



centerline2\_dev1

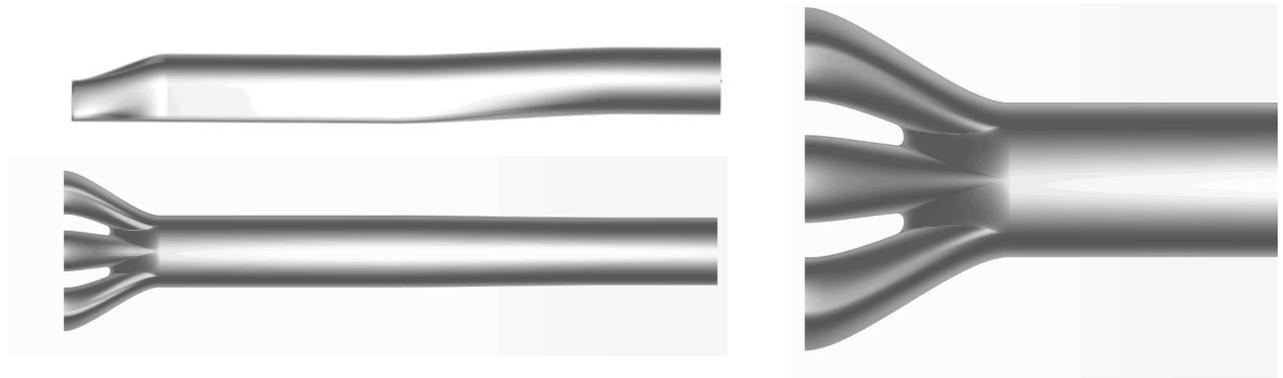


centerline2\_dev2

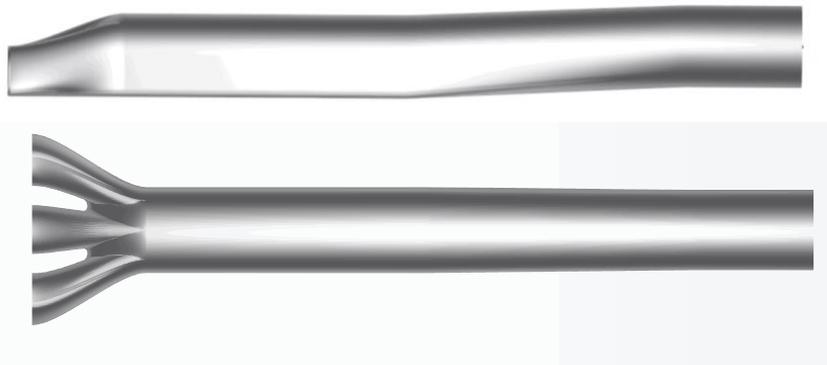


## 2. Creation of parametric models

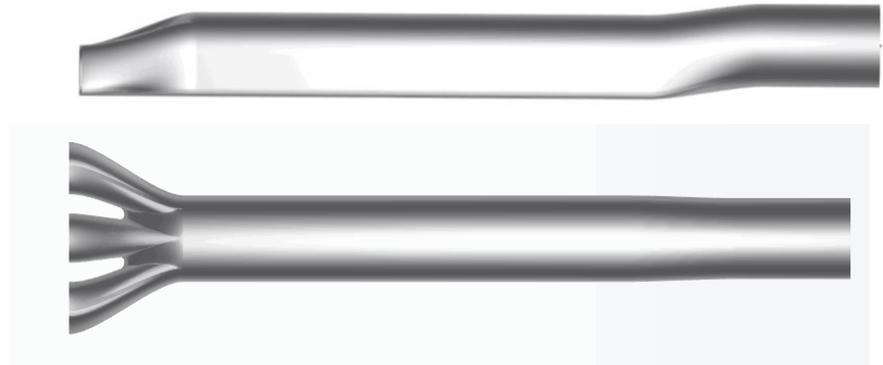
**Inlet\_AR:** affects the transition from inlet to channels



**inlet\_dev\_factor**

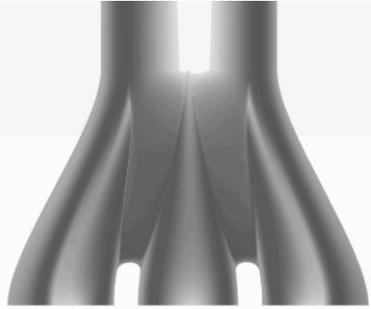


**inlet\_dev\_length**

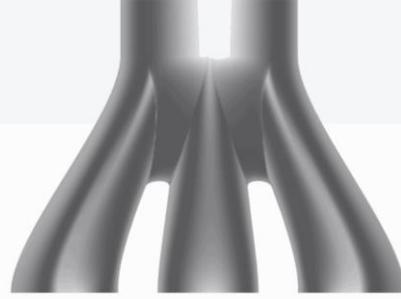


## 2. Creation of parametric models

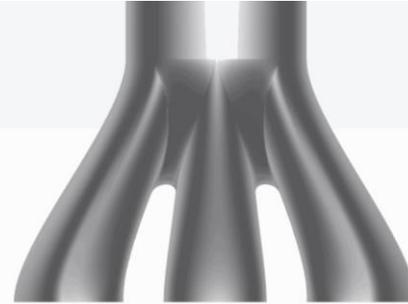
Junction\_Gap



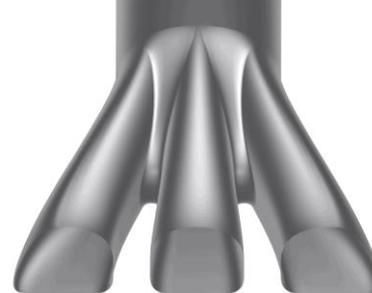
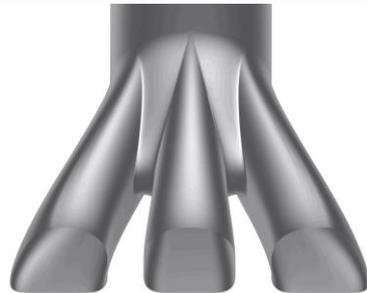
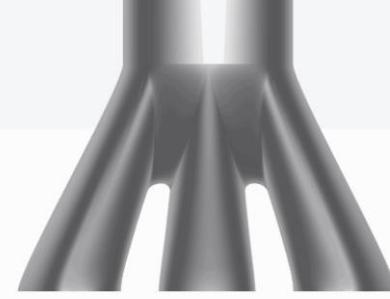
Junction\_Tongue



junction\_tongue\_verLoc

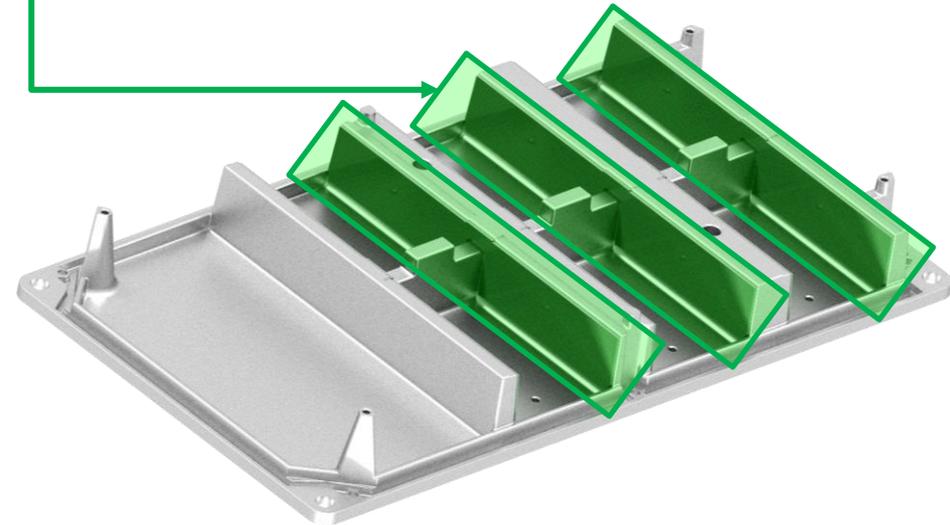
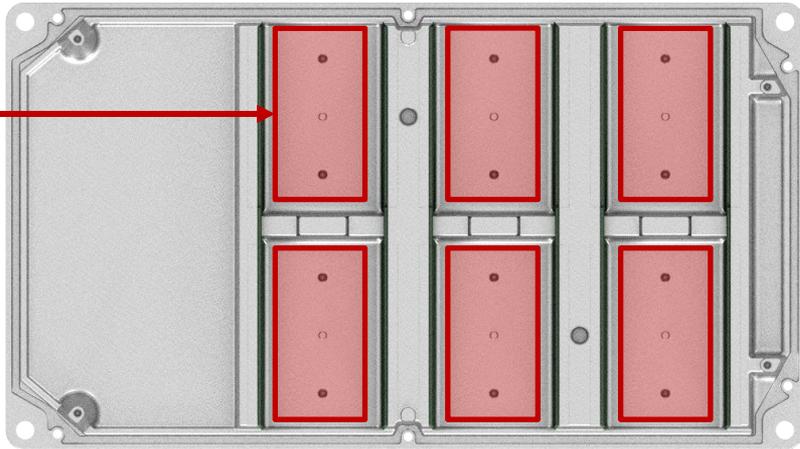


junction\_tongue\_horSF



## 3. Monitored quantities

- Pressure Drop across the coldplate
- Mass flow through each pipe
- Surface Average and Max temperature of inverter base
- Max temperature of transistors



## DOE

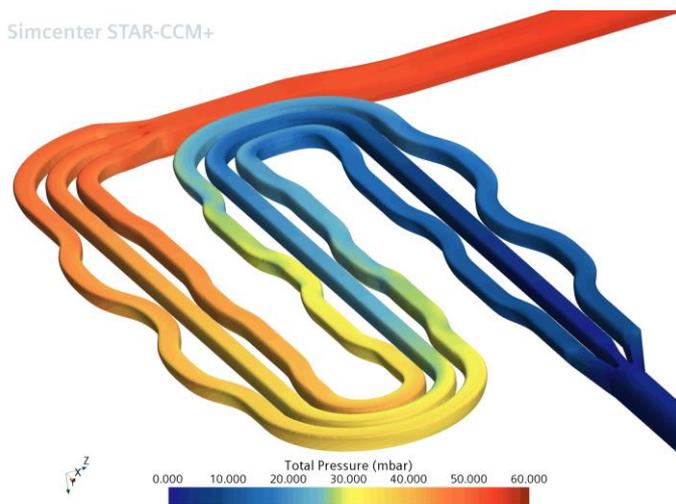
## OPTIMIZATION

A «Sobol» algorithm with 100 designs is run to extract Pearson's Correlation Coefficients

	Pressure Drop	MFR Channel 1	MFR Channel 2	MFR Channel 3	HTC	MAX Temperature Base	MAX Temperature Transistors	AVG Temperature Base
centerline1_dev1	-0.39	-0.28	-0.37	0.58	0.31	-0.05	-0.06	0.39
centerline1_dev2	-0.43	-0.23	-0.41	0.55	0.29	0.07	0.11	0.48
centerline2_dev1	-0.57	0.59	-0.59	-0.23	0.17	0.13	0.20	0.57
centerline2_dev2	-0.49	0.67	-0.49	-0.39	0.08	0.95	0.83	0.48
inlet_AR	0.19	-0.03	0.10	-0.05	-0.02	-0.14	-0.07	-0.18
inlet_devFactor	0.07	0.03	0.07	-0.09	-0.09	0.03	0.04	-0.03
inlet_devLength_par	-0.09	0.07	0.00	-0.08	0.04	0.01	-0.01	0.18
junction_h_SF	0.08	0.01	0.06	-0.06	-0.07	0.04	0.05	0.05
Tongue_SF	0.00	0.08	0.02	-0.10	0.12	-0.01	-0.05	-0.03
Tongue_vLoc_par	0.08	-0.23	0.18	0.12	-0.18	-0.12	-0.09	-0.08
junction_gap	0.20	0.14	0.13	-0.26	-0.08	0.18	0.21	-0.03

The monitored quantities are mainly affected by channel paths more than other parameters

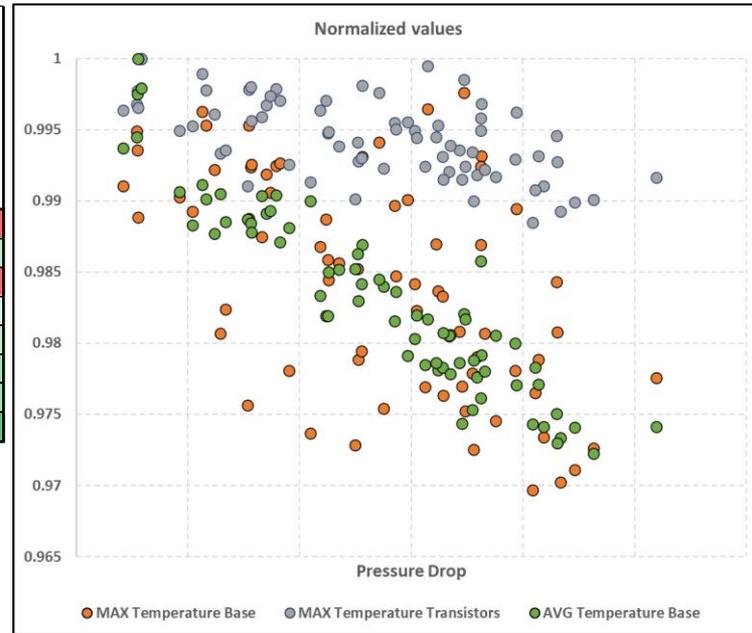
Simcenter STAR-CCM+



## DOE

## OPTIMIZATION

	Pressure Drop	MFR Channel 1	MFR Channel 2	MFR Channel 3	HTC	MAX Temperature Base	MAX Temperature Transistors	AVG Temperature Base
Pressure Drop	1.00	-0.44	0.98	-0.22	-0.40	-0.58	-0.58	-0.94
MFR Channel 1	-0.44	1.00	-0.48	-0.77	-0.04	0.69	0.66	0.41
MFR Channel 2	0.98	-0.48	1.00	-0.20	-0.38	-0.59	-0.60	-0.92
MFR Channel 3	-0.22	-0.77	-0.20	1.00	0.33	-0.34	-0.31	0.21
HTC	-0.40	-0.04	-0.38	0.33	1.00	0.04	-0.03	0.39
MAX Temperature Base	-0.58	0.69	-0.59	-0.34	0.04	1.00	0.96	0.59
MAX Temperature Transistors	-0.58	0.66	-0.60	-0.31	-0.03	0.96	1.00	0.59
AVG Temperature Base	-0.94	0.41	-0.92	0.21	0.39	0.59	0.59	1.00



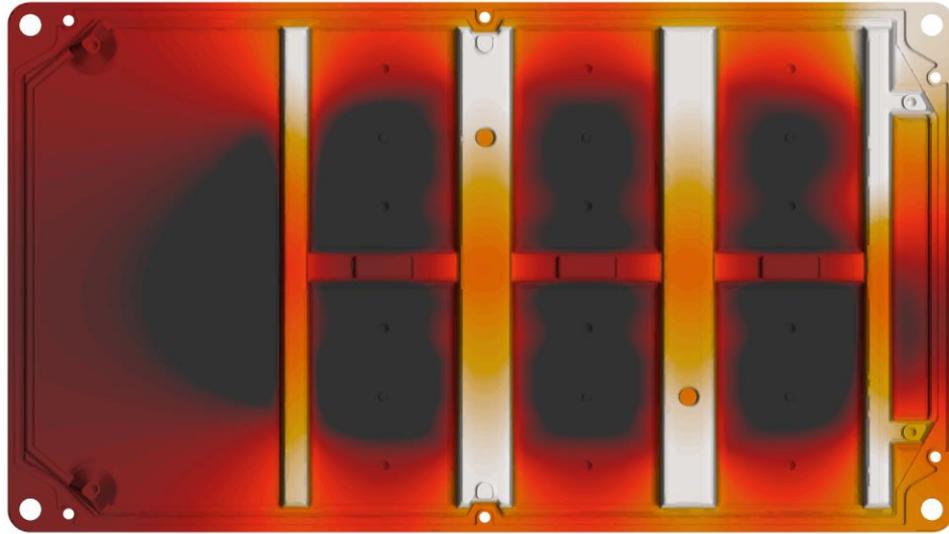
### Main outcomes:

- Pressure drop  $\uparrow$  Temperatures  $\downarrow$
- Pressure drop  $\uparrow$  MFR in channel 2  $\uparrow$
- All the temperatures all very well correlated  $\rightarrow$  just one can be picked to be minimized

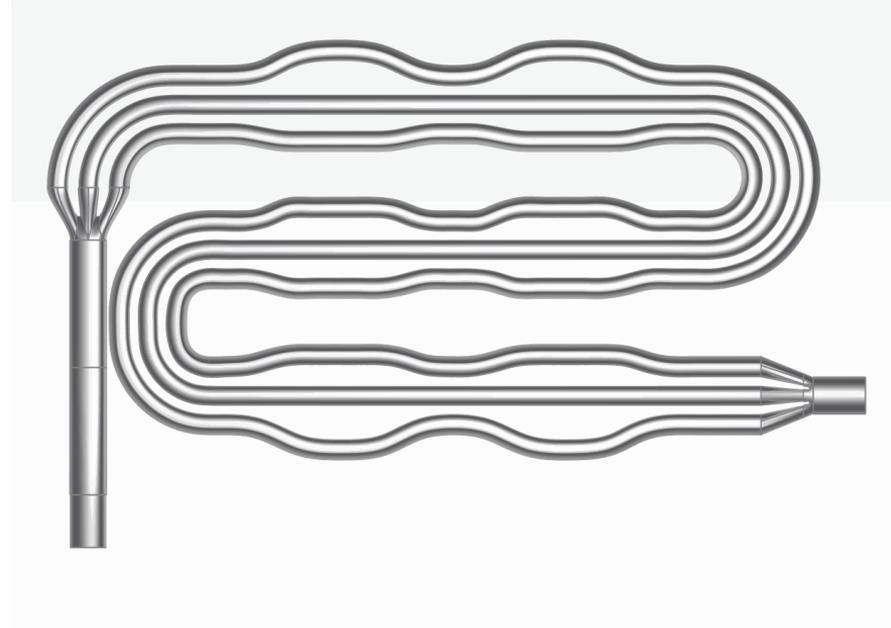
DOE

OPTIMIZATION

Simcenter STAR-CCM+



Temperature (C)  
40.000 43.333 46.667 50.000 53.333 56.667 60.000



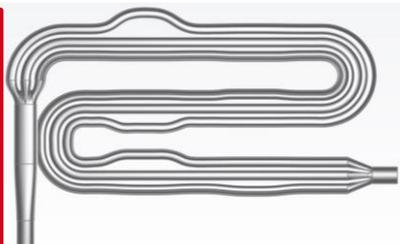
## DOE

## OPTIMIZATION

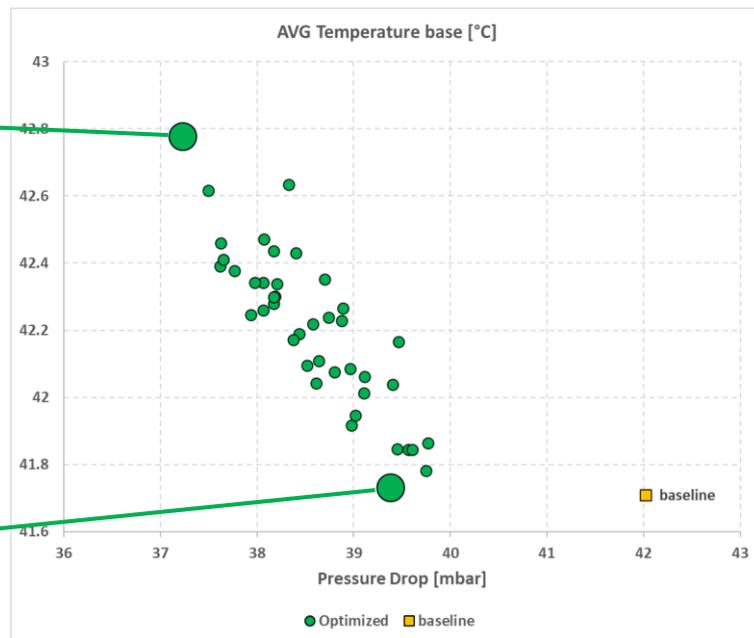
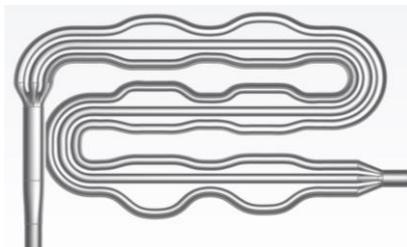
### Response surface optimization

- Two objectives: minimization of pressure drop and AVG Temperature base

Pressure drop reduction by more than **10%** in the most permeable configuration. Hence, in the actual operations, the flow rate through the cold plate will increase with a further reduction of temperatures.



The design with the minimum AVG temperature has the same temperature of baseline design with a reduction of pressure drop by more than 5%. Increased MFR is expected

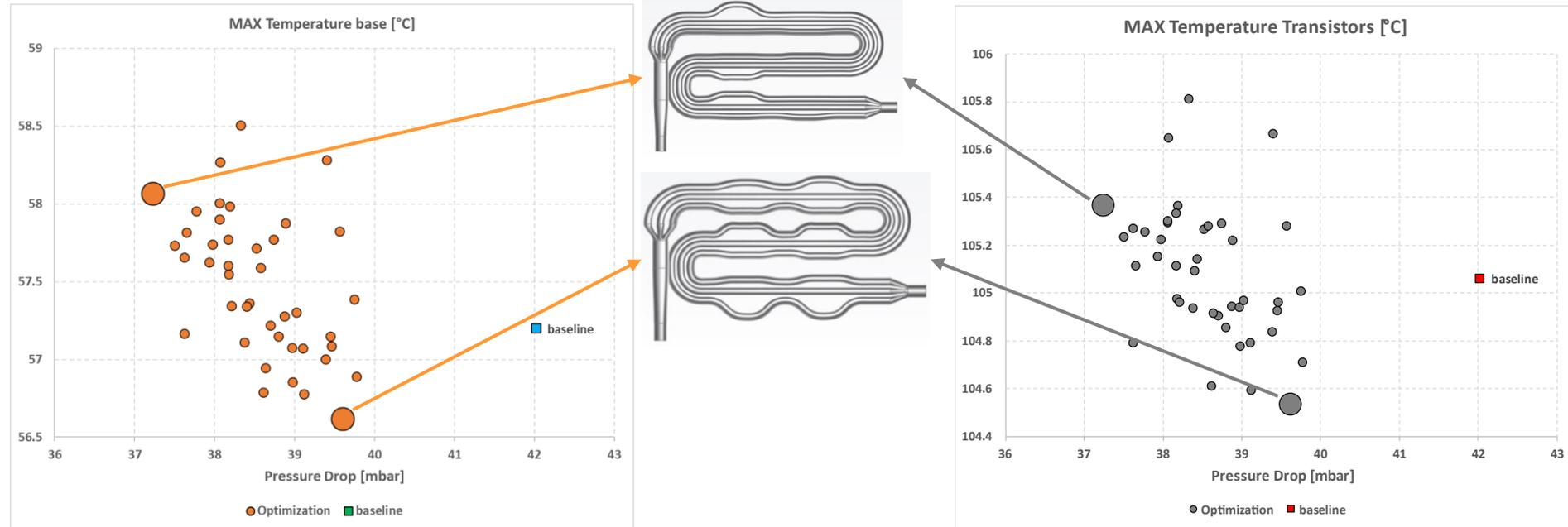


## DOE

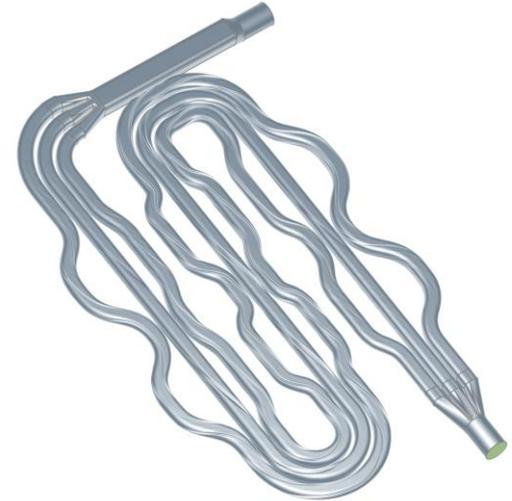
## OPTIMIZATION

### Response surface optimization

- The same rationale is valid looking at the best designs for MAX Temperature of base and transistors.



- *Was the optimization process successful?*
  - Yes, it was! The pressure drop reduction is the main outcome of the activity, which in turn leads to an increase of coolant flow rate and to a further temperature reduction
- *Why the temperature reduction was pretty limited?*
  - HTC x Area variation is limited, hence the heat removal capability of the coolant is unaltered
- *Are the shown designs feasible?*
  - Yes, they are! The cold plate will be engineered and pined to be tested on the Formula SAE car
- *Are there any other options?*
  - Yes, for sure! These results are of course influenced by the rationale of the model generation. Other kind of paths, pipe shapes, etc. can be tested: e.g., we tried to introduce parametric grooves on the pipe surface, but the increased pressure drop did not justify the minimal temperature decrease.





***Thank you for  
your attention!***



***Giuseppe Cicalese, PhD***  
***[giuseppe.cicalese@red-cfd.it](mailto:giuseppe.cicalese@red-cfd.it)***



***R&D CFD SRL***  
***Via Tacito, 59***  
***Modena - ITALY***

### *Acknowledgements*

*Thanks to MMR Hybrid Team for providing information to perform this activity and to Ceyhan Erdem for the parametric model generation*

